

## CLAIMS

1. A semiconductor device, comprising:

a semiconductor element;

5 a substrate having an upper surface on which said element is mounted and a bottom surface which is positioned on the opposite side;

a ratio H/L being 0.3 or greater, with L being the length in the long direction of a main surface of said semiconductor element, and H being the distance from a semiconductor element mounting part on said upper surface of  
10 said substrate to said bottom surface.

2. A semiconductor device as described in Claim 1, wherein:

said semiconductor element is a light emitting element;

a part of said substrate on which said element is mounted is formed as a cavity;

15 and a metal layer is formed on said upper surface.

3. A semiconductor device as described in Claim 2, wherein:

there is a connection member which connects between said substrate and a terminal plate which supplies power to said semiconductor light emitting element;

20 said connection member is placed at a position separate from said cavity;

a means for preventing infiltration of said connection member into said cavity is provided on said upper surface adjacent to said connection member.